

SMT505

High Performance Cyan color TOP LED

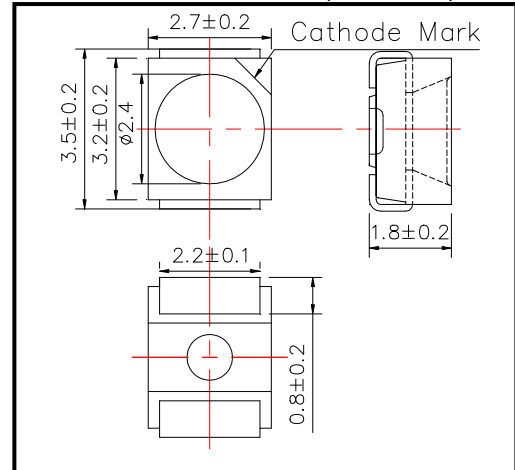
SMT505 consists of an InGaN LED mounted on the lead frame as TOP LED package and is 130mcd typical of Brightness.

It emits a spectral band of radiation at 505nm.

◆ Specifications

- 1) Product Name TOP LED
- 2) Type No. SMT505
- 3) Chip
- (1) Chip Material InGaN
- (2) Peak Wavelength 505nm typ.
- 4) Package
- (1) Lead Frame Die Silver Plated
- (2) Package Resin PPA Resin
- (3) Lens Epoxy Resin

◆ Outer dimension (Unit: mm)



◆ Absolute Maximum Ratings

Item	Symbol	Maximum Rated Value	Unit	Ambient Temperature
Power Dissipation	P _D	185	mW	T _a =25°C
Forward Current	I _F	50	mA	T _a =25°C
Reverse Voltage	V _R	5	V	T _a =25°C
Junction Temperature	T _J	100	°C	
Thermal Resistance	R _{thjp}	200	K/W	
Operating Temperature	T _{OPR}	-30 ~ +80	°C	
Storage Temperature	T _{STG}	-40 ~ +80	°C	
Soldering Temperature	T _{SOL}	250	°C	

‡Soldering condition: Soldering condition must be completed within 5 seconds at 250°C

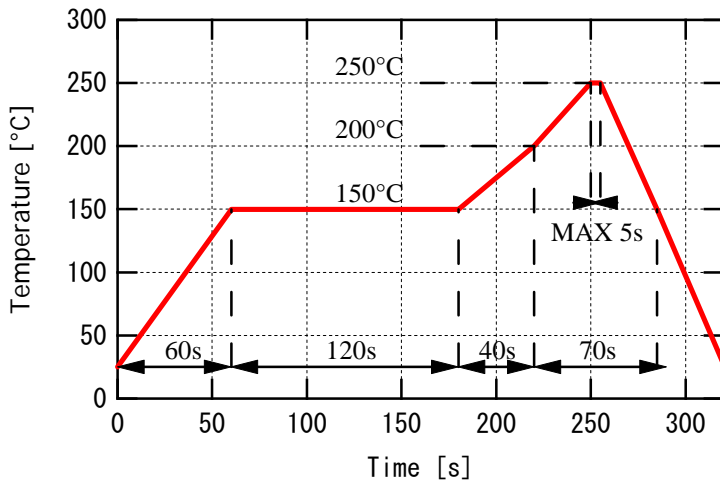
◆ Electro-Optical Characteristics [T_a=25°C]

Item	Symbol	Condition	Minimum	Typical	Maximum	Unit
Forward Voltage	V _F	I _F =20mA		3.3	4.0	V
Reverse Current	I _R	V _R =5V			10	uA
Total Radiated Power	P _O	I _F =20mA		10.0		mW
Brightness	I _V	I _F =20mA		130		mcd
Radiant Intensity	I _E	I _F =20mA		0.5		mW/sr
Peak Wavelength	λ _P	I _F =20mA	495	505	515	nm
Half Width	Δλ	I _F =20mA		30		nm
Viewing Half Angle	θ _{1/2}	I _F =20mA		±55		deg.

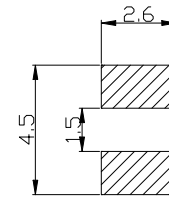
‡ Total Radiated Power is measured by Photodyne #500

‡Brightness is measured by Tektronix J-16.

◆ SMD Application
IR-Reflow Soldering Profile for lead free soldering

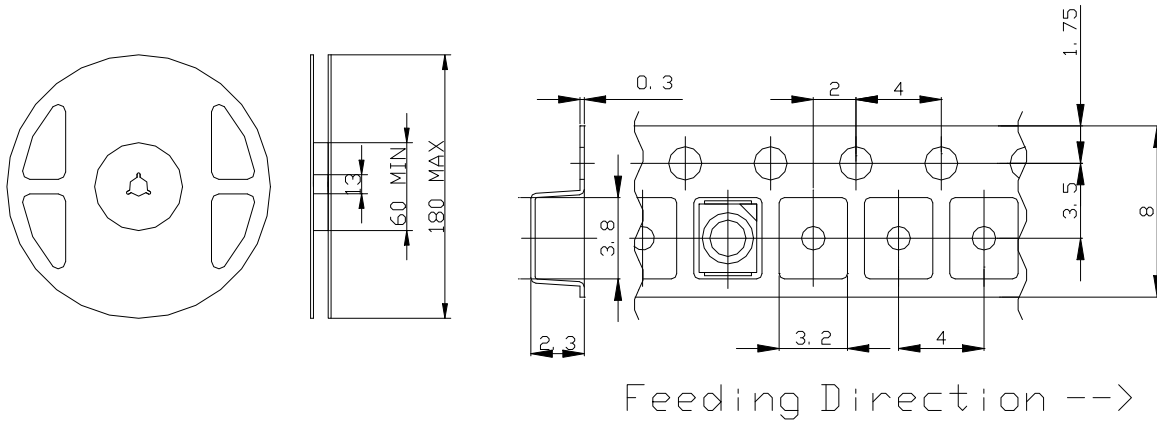


Recommended Land Layout (Unit: mm)



Don't put stress on SMD and a circuit board after soldering.

◆ SMD Packing
Tape and Reel Dimensions (Unit: mm)



◆ Wrapping

Moisture barrier bag aluminum laminated film with a desiccant to keep out the moisture absorption during the transportation and storage.